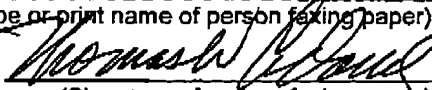


## CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being sent via facsimile to Examiner Gentle E. Winter at the facsimile number provided by the Examiner (703/746-7746) on the date shown below.

Date: September 17, 2002

Thomas W. Adams  
(Type or print name of person faxing paper)  
  
(Signature of person faxing paper)

MCGEP0179US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Dickson L. Whitney, Jr., et al.

Serial No: 09/628,036

Filed: July 27, 2000

For: **IMPROVED ADHESION OF POLYMERIC MATERIALS TO METAL SURFACES**

Art Unit: 1746

Examiner: Gentle E. Winter

SUPPLEMENTAL REPLY TO OFFICE ACTION MAILED APRIL 4, 2002

Box NON-FEE AMENDMENT  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

This paper is responsive to the Office Action mailed April 4, 2002 for which a first Reply was filed on July 2, 2002. The present paper is a Supplemental Reply, based on telephone interviews between the undersigned attorney and the Examiner in charge of this application. Entry of the amendments and allowance of the claims are respectfully requested.

Docket No. MCGEP0179US

Serial No. 09/628,036

**AMENDMENT****In the Claims:****Please amend claims 1, 3 and 43-52 to read as follows:**

1. (Twice Amended) A process for treating a metal substrate to improve adhesion of polymeric materials thereto, comprising the steps of  
intergranular etching a surface of the metal substrate; and  
applying an immersion plated metal to the intergranular etched surface by immersing the surface in an immersion plating composition comprising one or more plating metals selected from tin, silver, bismuth, copper, nickel, lead, zinc, indium, palladium, platinum, gold, cadmium, ruthenium, cobalt, gallium and germanium,

wherein the step of intergranular etching is carried out with an intergranular etching composition comprising

- B1
- (a) hydrogen peroxide;
  - (b) at least one acid, wherein the at least one acid comprises sulfuric acid or a sulfonic acid;
  - (c) at least one nitrogen-containing, five-membered heterocyclic compound which does not contain any sulphur, selenium or tellurium atom in the heterocycle; and
  - (d) at least one adhesive compound selected from sulfinic acids, seleninic acids, tellurinic acids, heterocyclic compounds containing at least one sulfur, selenium and/or tellurium atom in the heterocycle, and sulfonium, selenonium and telluronium salts having the general formula (A),

